

Swan thermal simulation conditions



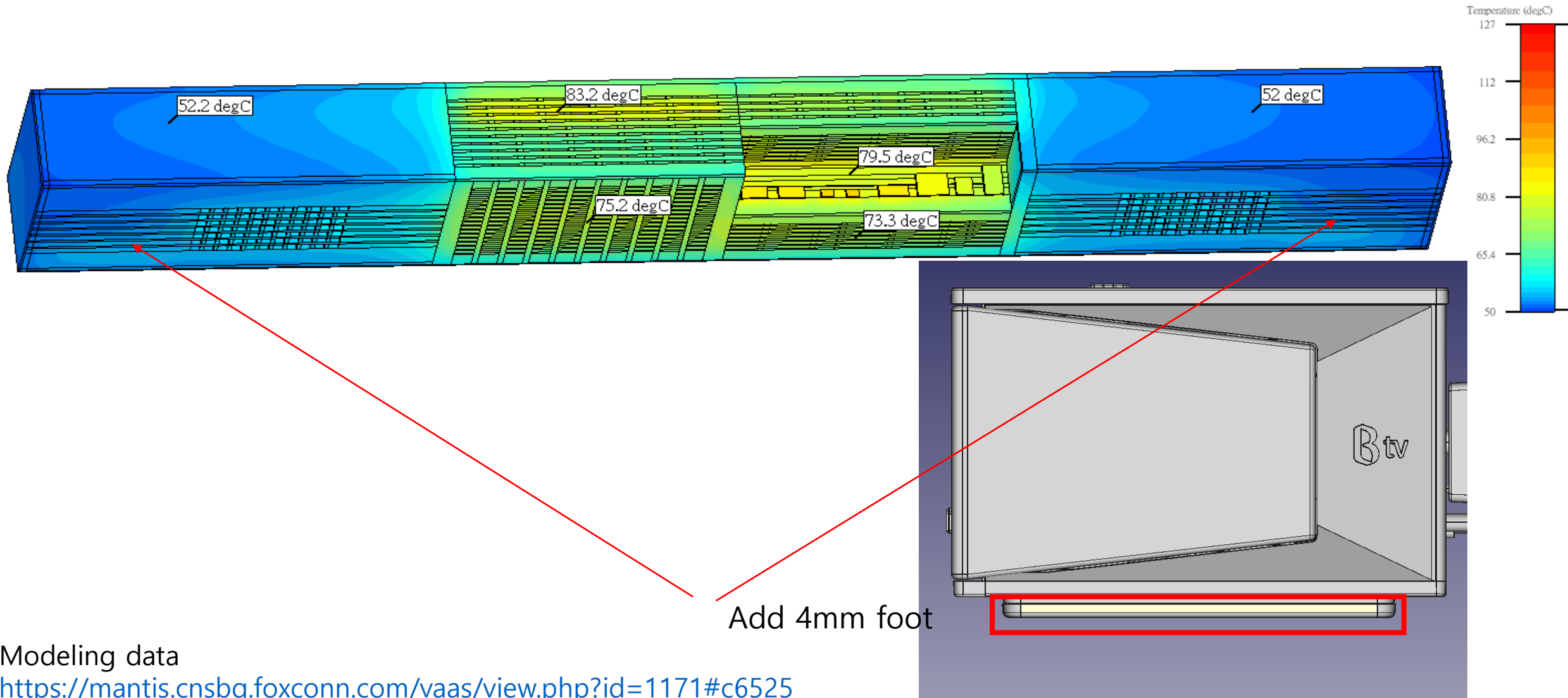
ALT Co., Ltd.

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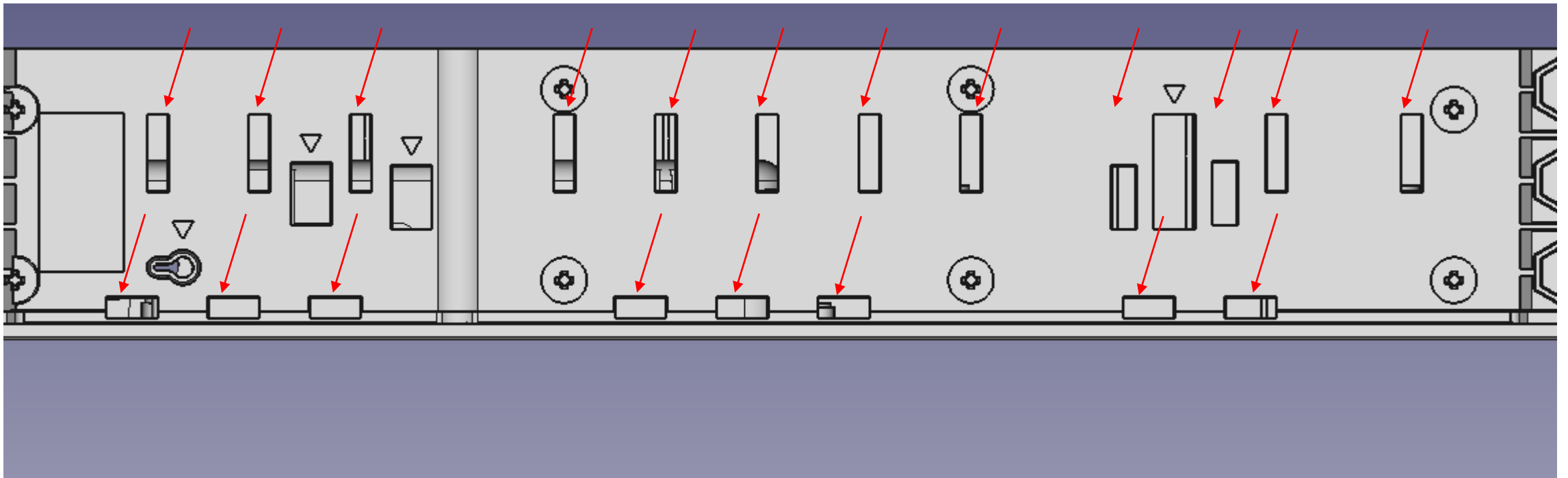
Ver.1.0

Issued by SH, SON

1. Add foot



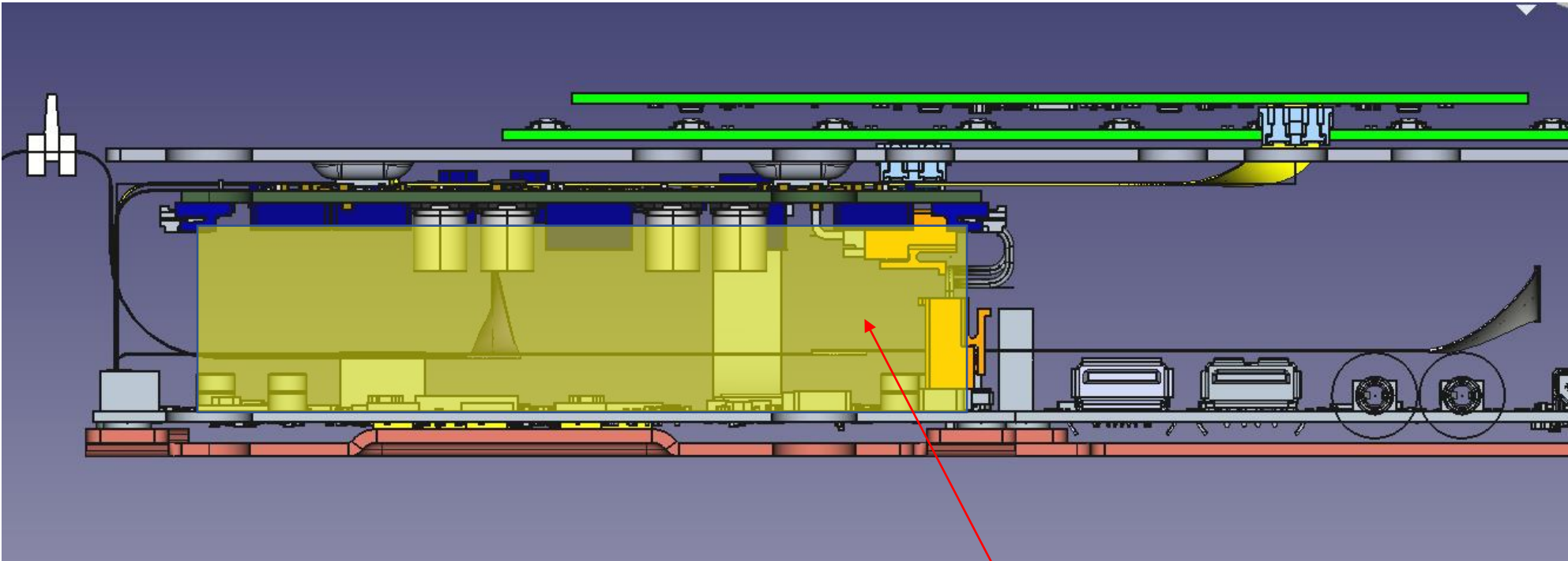
2. Add front side vent hole



Modeling data

<https://mantis.cnsbg.foxconn.com/vas/view.php?id=1171#c6525>

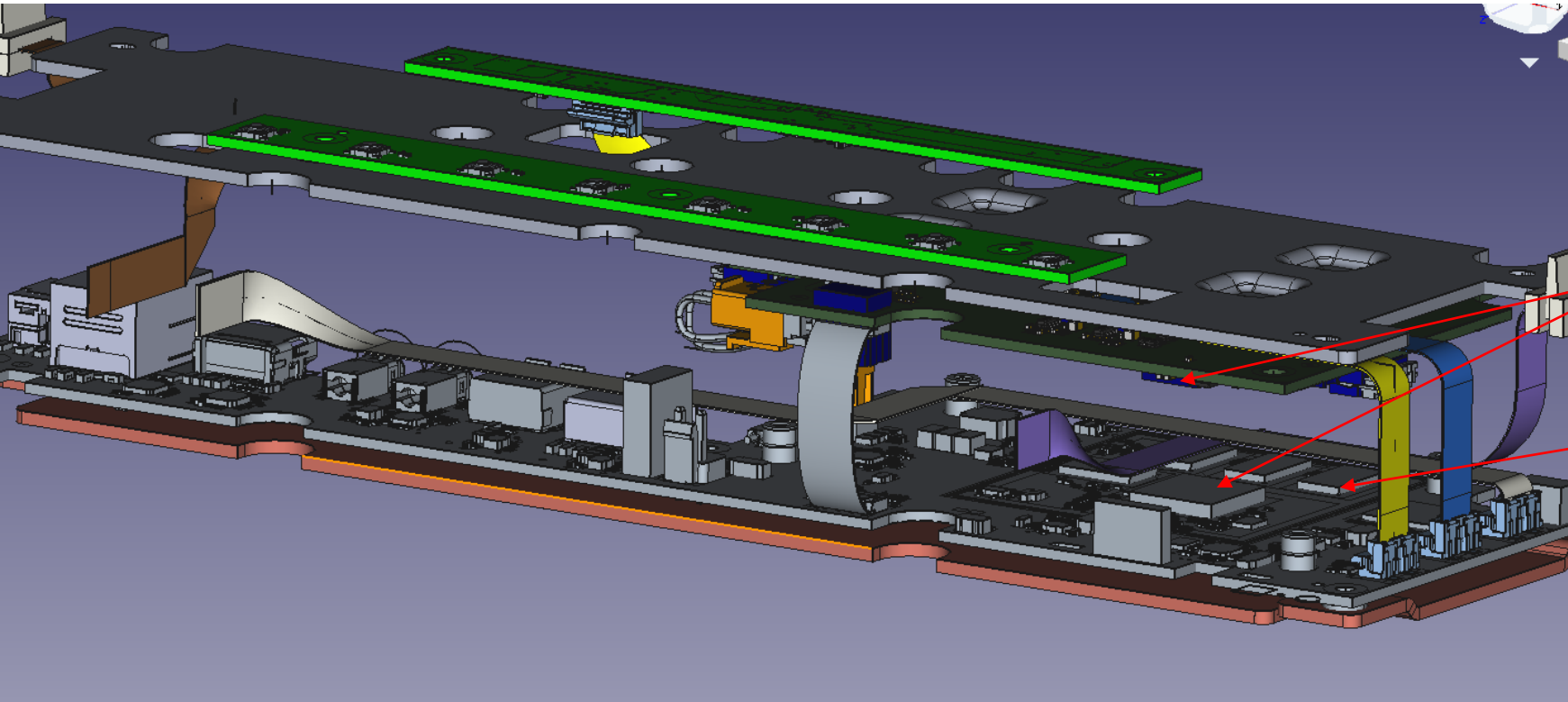
3. Remove inner heat spreader - add Aluminum die casting



1. Remove inner heat spreader : SoC TOP / Amp Top

2. Add AL diecasting between SoC (VS-550) Top and Amp Top (A113x)

4. Thermal conductivity change



1. SoC (VS550, A113X) Thermal pad change : 5w/mK -> 12w/mk
2. Memory Top side (DDR / EMMC) Thermal pad : Remove
3. The other thermal pad : maintain 5w/mk : SoC Bottom side, Amp Bottom side

5. The other conditions

The other conditions not mentioned at this document, remain the same as case-3

Case -3

Result

Ta = 50C (12mm)

Remove heat sink

Add bottom + rear vent holes

